SOT2104-1

HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.55 mm pitch, 11 mm x 11 mm x 0.85 mm body

8 March 2022 **Package information**

1   Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN124
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-08-2014
Manufacturer package code	MV-A300948-00A

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.9	11	11.1	mm
package width	10.9	11	11.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.55	-	mm
actual quantity of termination	-	124	-	

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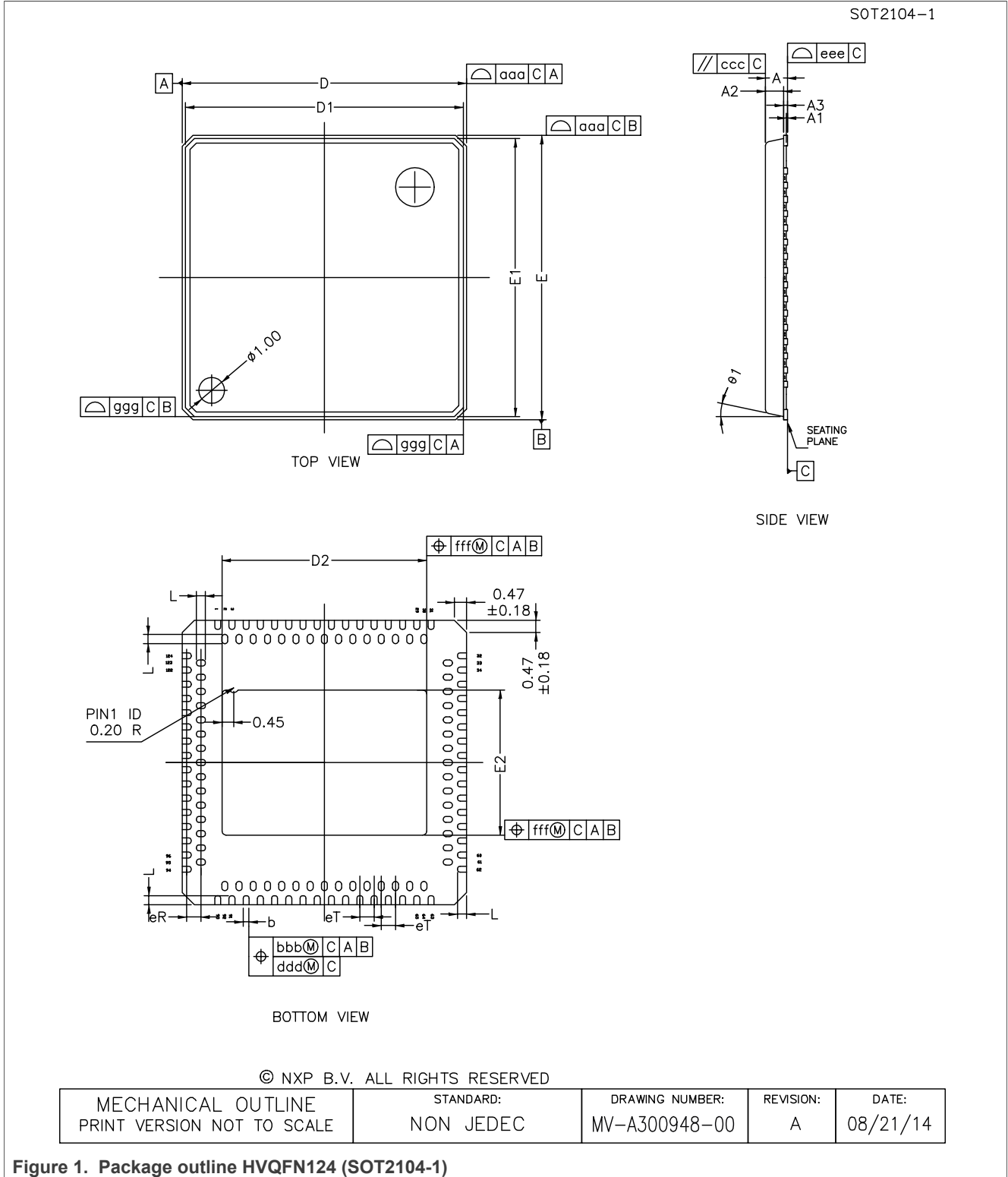
2 Package outline

Figure 1. Package outline HVQFN124 (SOT2104-1)

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SYMBOL	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.80	0.85	0.90
A1	0.00	0.01	0.05
A2	0.65	0.70	0.75
A3	0.152 REF.		
b	0.18	0.23	0.28
D	10.9	11.0	11.1
D1	10.65	10.75	10.85
D2	7.817	7.917	8.017
E	10.9	11.0	11.1
E1	10.65	10.75	10.85
E2	5.511	5.611	5.711
L	0.25	0.35	0.45
eT	0.55 bsc		
eR	0.55 bsc		
θ1	5˙	―――	15˙
R	0.090	―――	―――
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		
ggg	0.20		

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIE THICKNESS ALLOWABLE IS 0.305 mm MAXIMUM(.012 INCHES MAXIMUM)
3. DIMENSIONING & TOLERANCES CONFORM TO ASME Y14.5M. −1994.
4. DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINALTIP.
5. THE PIN #1 IDENTIFIER MUST BE PLACED ON THE TOP SURFACE OF THE
    PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. PACKAGE WARPAGE MAX 0.08 mm.
8. APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING.
9. APPLIED ONLY TO TERMINALS.
10. PACKAGE CORNERS UNLESS OTHERWISE SPECIPIED ARE R0.175±0.025 mm.

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: MV−A300948−00	REVISION: A	DATE: 08/21/14

Figure 2. Package outline note HVQFN124 (SOT2104-1)

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3   Legal information

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